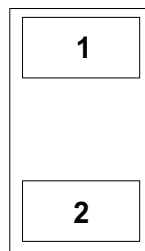


# AQHVxx-01ETG-C

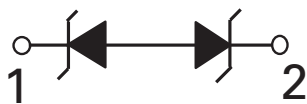
## General Purpose ESD Protection



### Pinout



### Functional Block Diagram



## Description

The AQHVxx-01ETG-C series is designed to provide an option for very fast acting, high performance over-voltage protection components. This series is ideally suited for power interfaces, passenger charging interfaces, and well as LED lighting modules, and low speed I/Os. It will protect sensitive equipment from damage due to electrostatic discharge (ESD) and other overvoltage transients.

The AQHVxx-01ETG-C series can safely absorb repetitive ESD strikes above the maximum level of the IEC 61000-4-2 international standard (Level 4,  $\pm 8\text{kV}$  contact discharge) without performance degradation and safely conduct up to 8A (AQHV12-C) of induced surge current (IEC 61000-4-5 2nd edition,  $t_P=8/20\mu\text{s}$ ) with very low clamping voltages.

## Features & Benefits

- ESD, IEC 61000-4-2,  $\pm 30\text{kV}$  contact,  $\pm 30\text{kV}$  air
- EFT, IEC 61000-4-4, 40A 5/50ns)
- Lightning, IEC 61000-4-5 2nd Edition, 8A (8/20us) for AQHV12-C
- Low clamping voltage
- PPAP capable
- Low leakage current
- Small SOD882 packaging helps save board space
- AEC-Q101 qualified
- Moisture Sensitivity Level(MSL -1)
- Halogen free, lead free and RoHS compliant

## Applications

- LED Lighting Modules
- Portable Instrumentation
- General Purpose I/O
- RS232 / RS485
- CAN and LIN Bus
- Automotive application

Life Support Note:

### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

# AQHVxx-01ETG-C

## General Purpose ESD Protection

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$P_{pk}$	Peak Pulse Power ( $t_p=8/20\mu s$ )	200	W
$T_{OP}$	Operating Temperature	-40 to 150	$^{\circ}C$
$T_{STOR}$	Storage Temperature	-55 to 150	$^{\circ}C$

**Caution:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### AQHV12-C Electrical Characteristics ( $T_{OP}=25^{\circ}C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	$I_R=1\mu A$			12.0	V
Breakdown Voltage	$V_{BR}$	$I_R=1mA$	13.3			V
Reverse Leakage Current	$I_{LEAK}$	$V_R=12V$			1.0	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$			19.0	V
		$I_{PP}=8A, t_p=8/20\mu s, Fwd$			25.0	V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p=100ns, I/O$ to GND		0.48		$\Omega$
Peak Pulse Current	$I_{PP}$	$t_p=8/20\mu s$			8.0	A
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 30$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_{I/O-I/O}$	Reverse Bias=0V, f=1MHz			30	pF

### AQHV15-C Electrical Characteristics ( $T_{OP}=25^{\circ}C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	$I_R=1\mu A$			15.0	V
Breakdown Voltage	$V_{BR}$	$I_R=1mA$	16.7			V
Reverse Leakage Current	$I_{LEAK}$	$V_R=15V$			1.0	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$			22.0	V
		$I_{PP}=5A, t_p=8/20\mu s, Fwd$			30.0	V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p=100ns, I/O$ to GND		0.43		$\Omega$
Peak Pulse Current	$I_{PP}$	$t_p=8/20\mu s$			5.0	A
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 30$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_{I/O-I/O}$	Reverse Bias=0V, f=1MHz			24	pF

# AQHVxx-01ETG-C

## General Purpose ESD Protection

### AQHV24-C Electrical Characteristics (T<sub>OP</sub>=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V <sub>RWM</sub>	I <sub>R</sub> =1μA			24.0	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>R</sub> =1mA	26.7			V
Reverse Leakage Current	I <sub>LEAK</sub>	V <sub>R</sub> =24V			1.0	μA
Clamp Voltage <sup>1</sup>	V <sub>C</sub>	I <sub>PP</sub> =1A, t <sub>p</sub> =8/20μs, Fwd			36.0	V
		I <sub>PP</sub> =3A, t <sub>p</sub> =8/20μs, Fwd			50.0	V
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, t <sub>p</sub> =100ns, I/O to GND		0.65		Ω
Peak Pulse Current	I <sub>PP</sub>	t <sub>p</sub> =8/20μs			3.0	A
ESD Withstand Voltage <sup>1</sup>	V <sub>ESD</sub>	IEC 61000-4-2 (Contact Discharge)	±24			kV
		IEC 61000-4-2 (Air Discharge)	±30			kV
Diode Capacitance <sup>1</sup>	C <sub>I/O-I/O</sub>	Reverse Bias=0V, f=1MHz			17	pF

### AQHV36-C Electrical Characteristics (T<sub>OP</sub>=25°C)

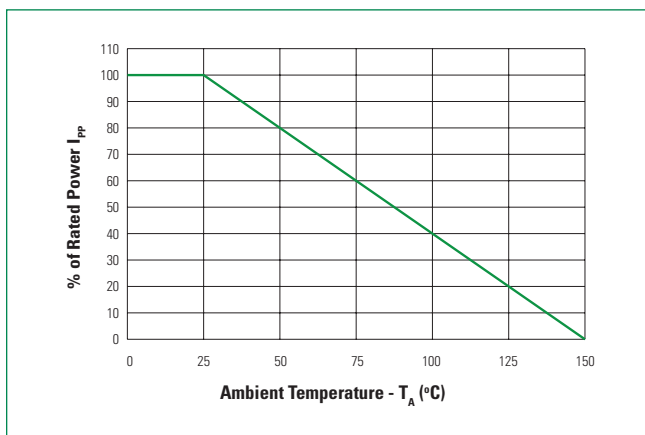
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V <sub>RWM</sub>	I <sub>R</sub> =1μA			36.0	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>R</sub> =1mA	40.0			V
Reverse Leakage Current	I <sub>LEAK</sub>	V <sub>R</sub> =36V			1.0	μA
Clamp Voltage <sup>1</sup>	V <sub>C</sub>	I <sub>PP</sub> =1A, t <sub>p</sub> =8/20μs, Fwd			52.0	V
		I <sub>PP</sub> =2A, t <sub>p</sub> =8/20μs, Fwd			65.0	V
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, t <sub>p</sub> =100ns, I/O to GND		1.33		Ω
Peak Pulse Current	I <sub>PP</sub>	t <sub>p</sub> =8/20μs			2.0	A
ESD Withstand Voltage <sup>1</sup>	V <sub>ESD</sub>	IEC 61000-4-2 (Contact Discharge)	±15			kV
		IEC 61000-4-2 (Air Discharge)	±20			kV
Diode Capacitance <sup>1</sup>	C <sub>I/O-I/O</sub>	Reverse Bias=0V, f=1MHz			13	pF

**Note:**

<sup>1</sup> Parameter is guaranteed by design and/or component characterization.

<sup>2</sup> Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window t1=70ns to t2= 90ns

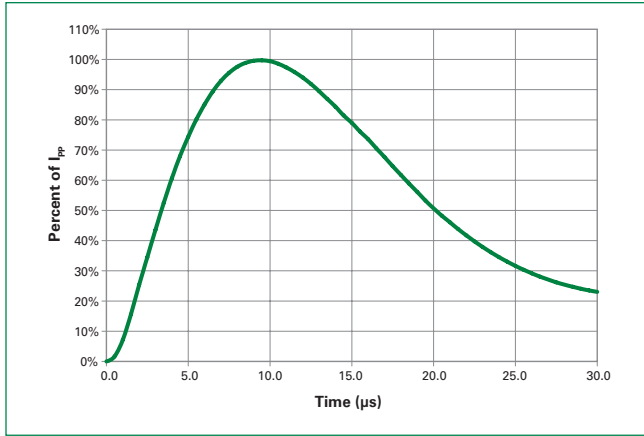
### Power Derating Curve



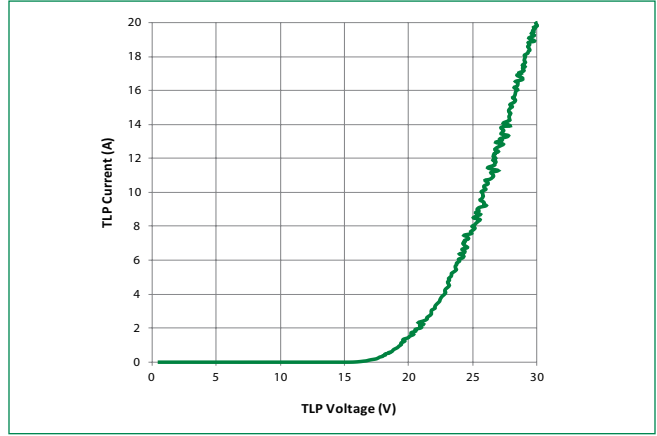
# AQHVxx-01ETG-C

## General Purpose ESD Protection

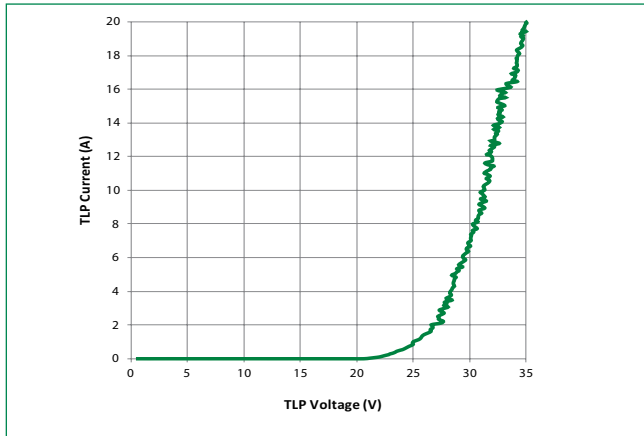
**8/20µs Pulse Waveform**



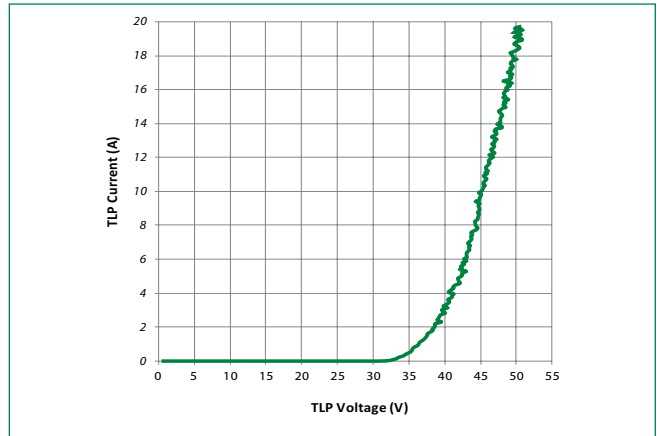
**AQHV12-C Transmission Line Pulsing(TLP) Plot**



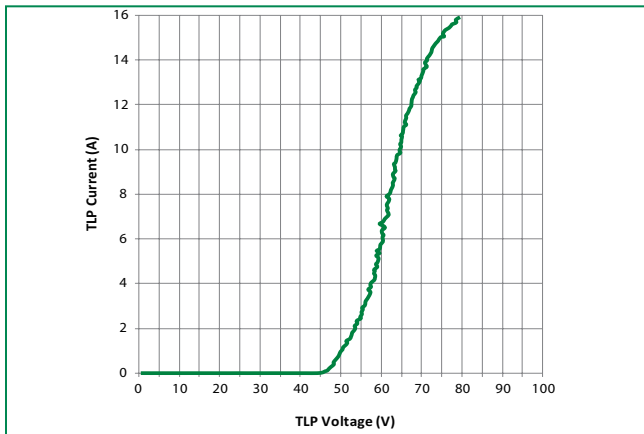
**AQHV15-C Transmission Line Pulsing(TLP) Plot**



**AQHV24-C Transmission Line Pulsing(TLP) Plot**



**AQHV36-C Transmission Line Pulsing(TLP) Plot**

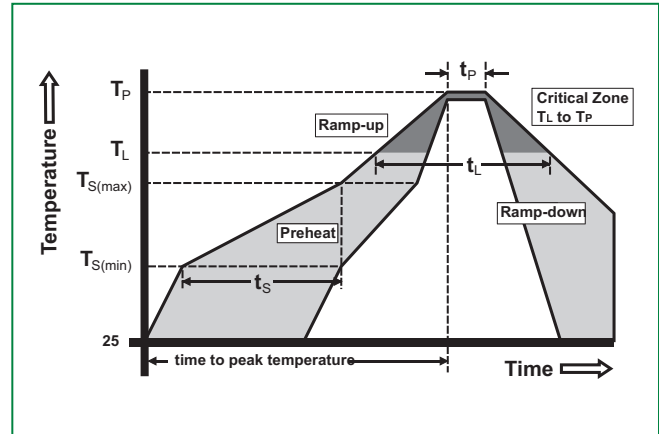


# AQHVxx-01ETG-C

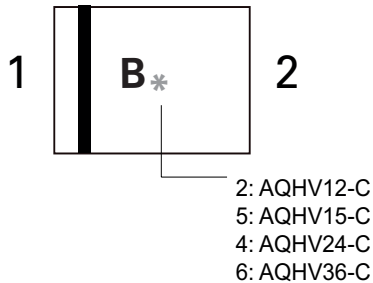
## General Purpose ESD Protection

### Soldering Parameters

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 120 secs
<b>Average ramp up rate (Liquidus) Temp (<math>T_L</math>) to peak</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		30 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C



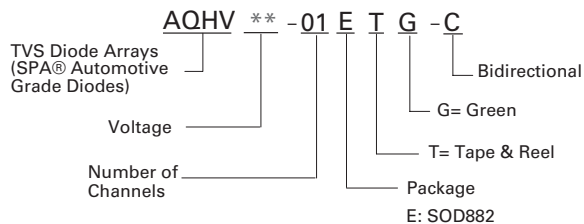
### Part Marking System



### Product Characteristics

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Substrate Material</b>	Silicon
<b>Body Material</b>	Molded Compound
<b>Flammability</b>	UL Recognized compound meeting flammability rating V-0

### Part Numbering System



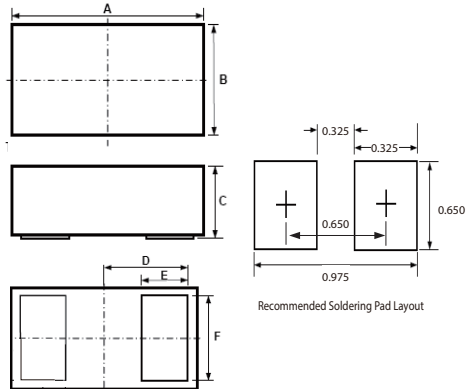
### Ordering Information

Part Number	Package	Min. Order Qty.
AQHV12-01ETG-C	SOD882	10000
AQHV15-01ETG-C		
AQHV24-01ETG-C		
AQHV36-01ETG-C		

# AQHVxx-01ETG-C

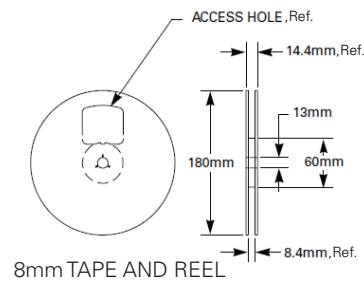
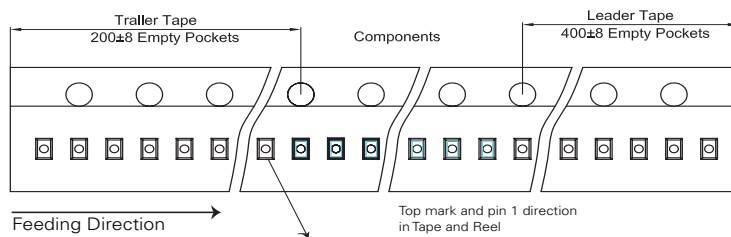
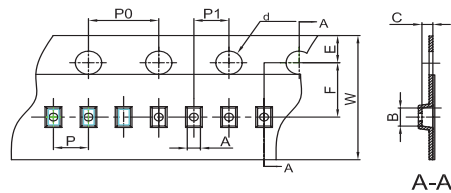
## General Purpose ESD Protection

### Package Dimensions — SOD882



Symbol	Package	SOD882				
	JEDEC	MO-236				
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.90	1.00	1.10	0.037	0.039	0.041
B	0.50	0.60	0.70	0.022	0.024	0.026
C	0.40	0.50	0.60	0.016	0.020	0.024
D		0.45		0.018		
E	0.20	0.25	0.35	0.008	0.010	0.012
F	0.45	0.50	0.55	0.018	0.020	0.022

### Embossed Carrier Tape & Reel Specification



Symbol	Millimeters
A	0.70+/-0.045
B	1.10+/-0.045
C	0.65+/-0.045
d	1.55+/-0.10
E	1.75+/-0.05
F	3.50+/-0.05
P	2.00+/-0.10
P0	4.00+/-0.10
P1	2.00+/-0.10
W	8.00 + 0.30 -0.10

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